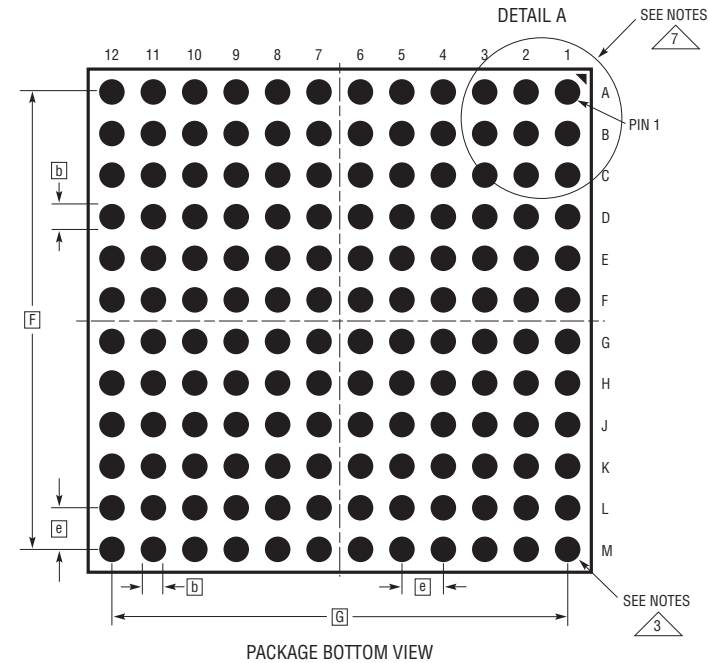
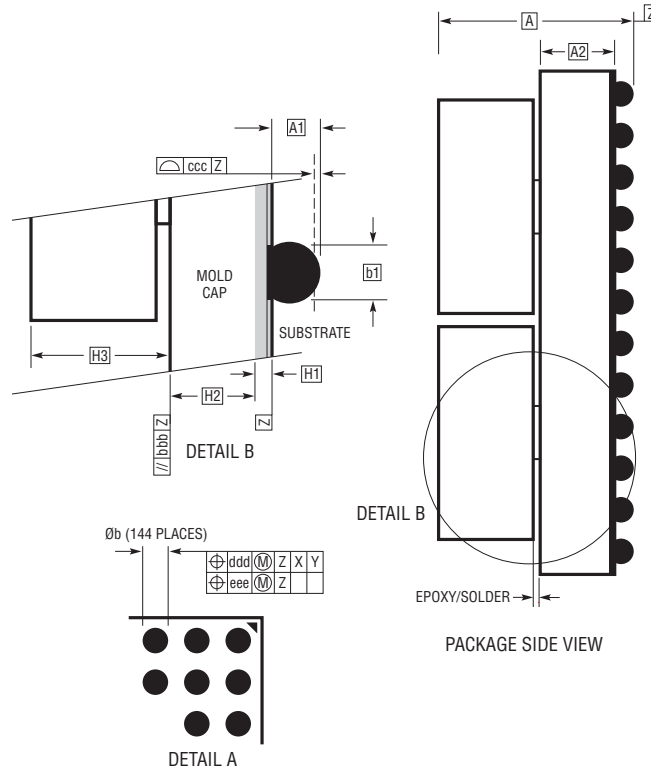
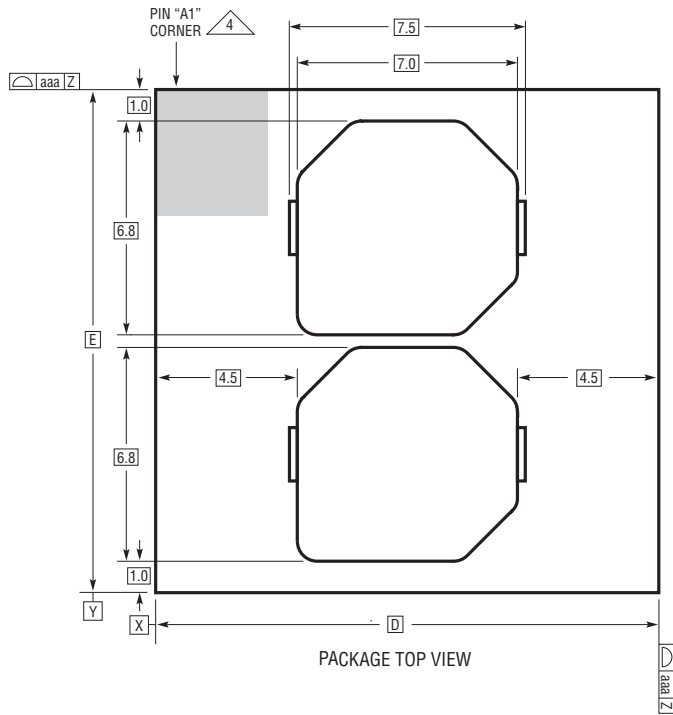


**BGA Package**  
**144-Lead (16mm × 16mm × 6.07mm)**  
 (Reference LTC DWG # 05-08-1540 Rev A)



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

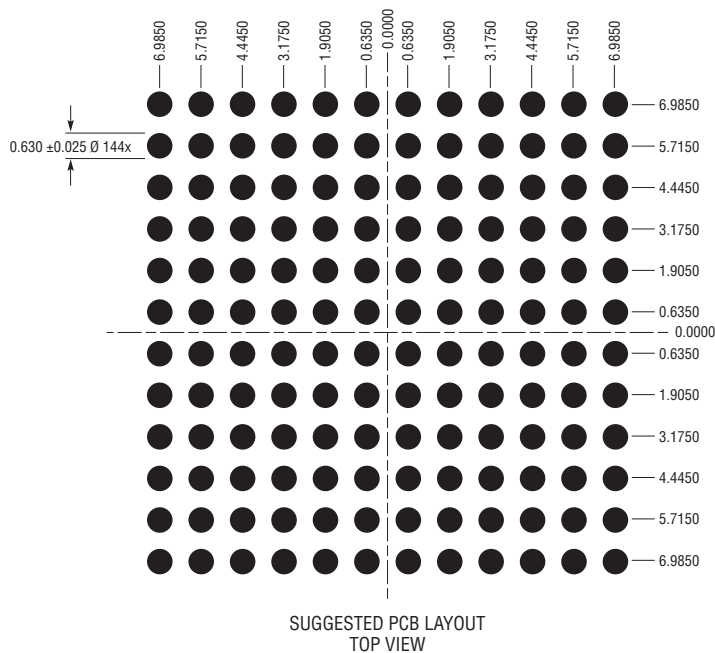
3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu

7  PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	5.78	6.07	6.36	
A1	0.50	0.60	0.70	
A2	2.23	2.32	2.41	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D		16.00		
E		16.00		
e		1.27		
F		13.97		
G		13.97		
H1	0.28	0.32	0.36	sub thick.
H2	1.95	2.00	2.05	mold cap ht.
H3	3.05	3.15	3.25	IND ht.
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 144				

